MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

IBGA89 8x9
CASE 503CM
ISSUE A

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NOTES:
2. CONTROLLING DIMENSION: MILLIMETERS [inches].
3. BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CRONWS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CRONWS OF THE SOLDER BALLS.
6. GLASS: 0.800 ±0.020, RESIN: 0.85 ±0.050, I. D. 0.458 ±0.000 (SIX SIDED),
7. AIR GAP BETWEEN GLASS AND PKGarray: 0.125 +0.000.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUM A AND B 15° ± 0.5°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PKGarray DEFINITIONS.
11. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (+0.313, 0.217),
12. PACKAGE CENTER (X, Y) = (0.000, 0.000).

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**GENERIC MARKING DIAGRAM**

- **XXXX** = Specific Device Code
- **Y** = Year
- **ZZZ** = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, “G” or microdot “✓”, may or may not be present. Some products may not follow the Generic Marking.*